

7. (Amended) A tiedown structure comprising:
a semiconductor substrate having a chip formed thereon;
an edge seal along an outer perimeter of the chip; and
a conductive connector forming an electrical connection between the edge seal and a
portion of the chip.

10. (Amended) A method for forming a tiedown structure, comprising:
forming a device on a chip;
defining a kerf proximate the chip; and
forming an electrically conductive connector, the conductive connector connecting the
device and the kerf.

17. (Once Amended) A method for forming a tiedown structure, comprising:
forming a chip on a semiconductor substrate, the chip including a device;
forming an edge seal along an outer perimeter of the chip; and
forming an electrically conductive connector, the conductive connector connecting the
edge seal and the device.--